



Click [here](#) for the 3D model.

General Information

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| Series | SMD Comm X7R FO |
| Style | SMD Chip |
| Description | SMD, MLCC, Open Mode, Temperature Stable |
| Features | Open Mode, Temperature Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 41 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

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|-----------|-----------------|
| Chip Size | 1206 |
| L | 3.2mm +/-0.2mm |
| W | 1.6mm +/-0.2mm |
| T | 1.6mm +/-0.20mm |
| S | 1.5mm MIN |
| B | 0.5mm +/-0.25mm |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 330mm, Plastic Tape |
| Packaging Quantity | 8000 |

Specifications

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|--|---|
| Capacitance | 4.7 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 16 VDC |
| Dielectric Withstanding Voltage | 40 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 3.5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 106.4 MOhms |

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